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(12) **United States Design Patent**  
**Lin et al.**

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(45) **Date of Patent:** **\*\* Jan. 15, 2013**

(54) **LED PACKAGE**

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/417,133**

(22) Filed: **Mar. 30, 2012**

(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/180**

(58) **Field of Classification Search** ..... D13/180;  
D26/1, 2; 257/79, 80, 81, 88, 89, 95, 98,  
257/99, 100, E33.058; 313/483, 498, 500;  
362/555, 800

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a “LED package,” as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a “LED package” showing my new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a left side view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a top view thereof;

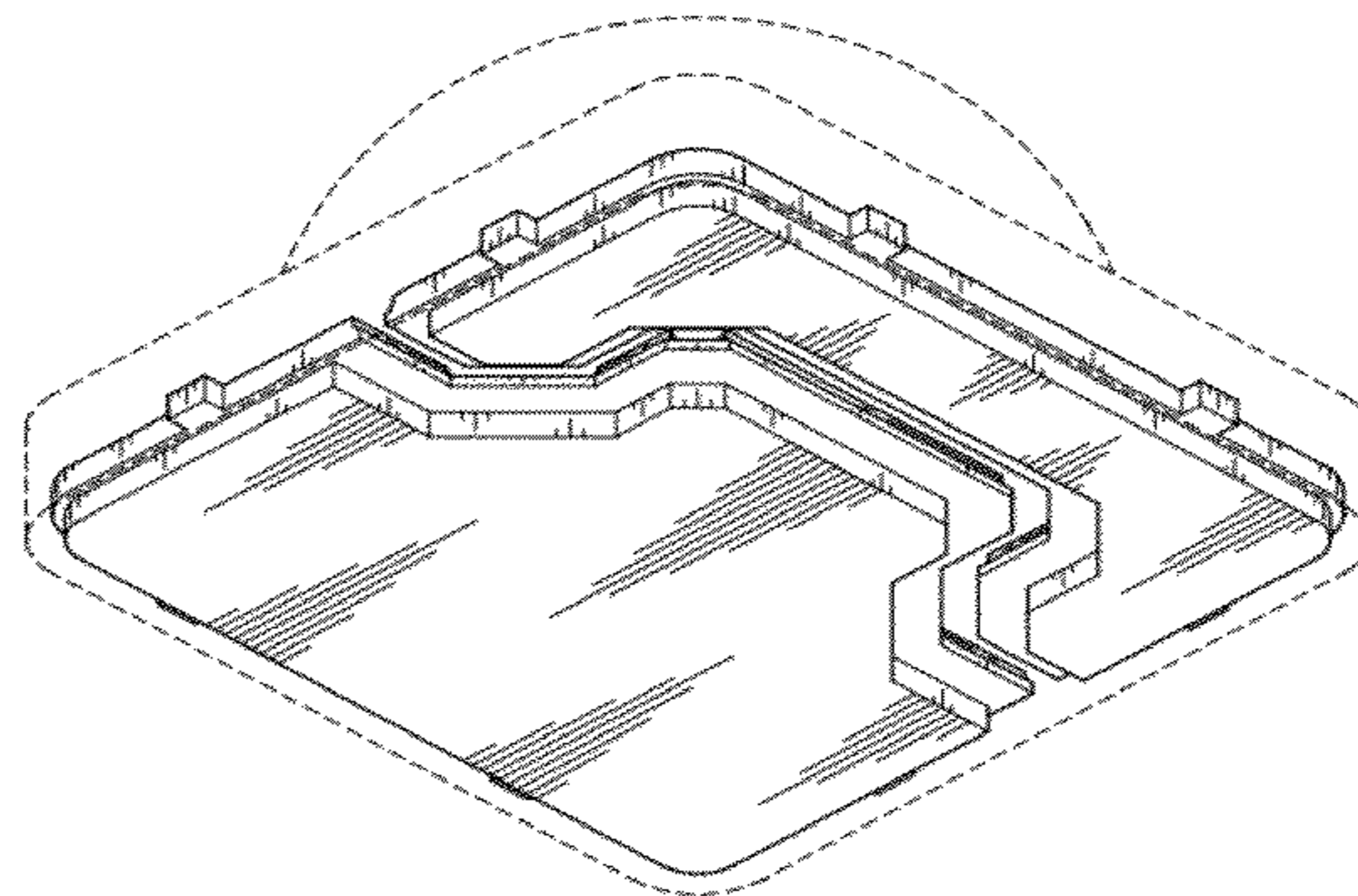
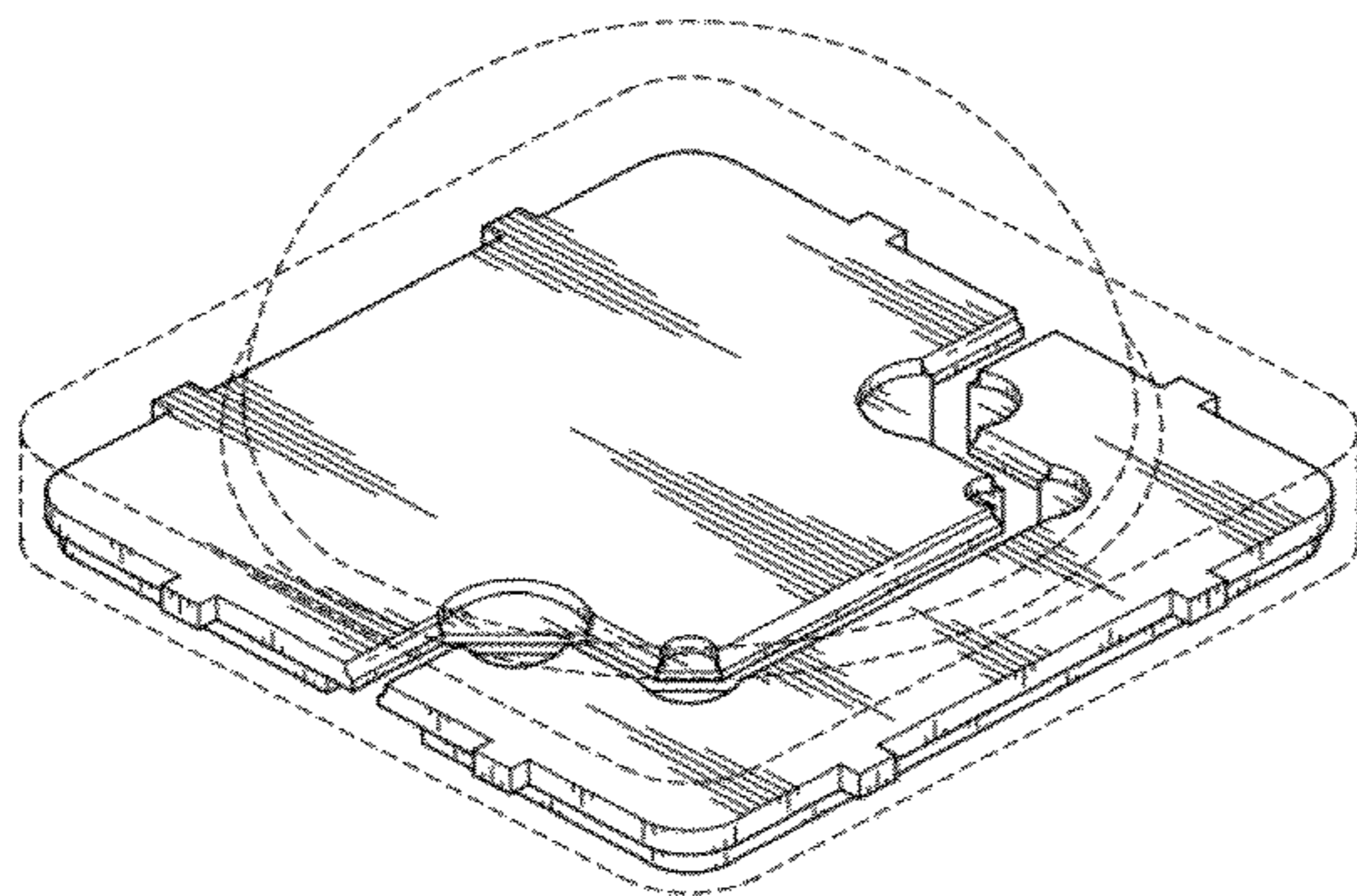
FIG. 7 is a bottom view thereof; and

FIG. 8 is a perspective view viewed from another visual angle thereof; and,

FIG. 9 is a perspective view with a LED chip showing the practical usage thereof.

The dashed lines in the drawings are for illustrative purpose only and form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



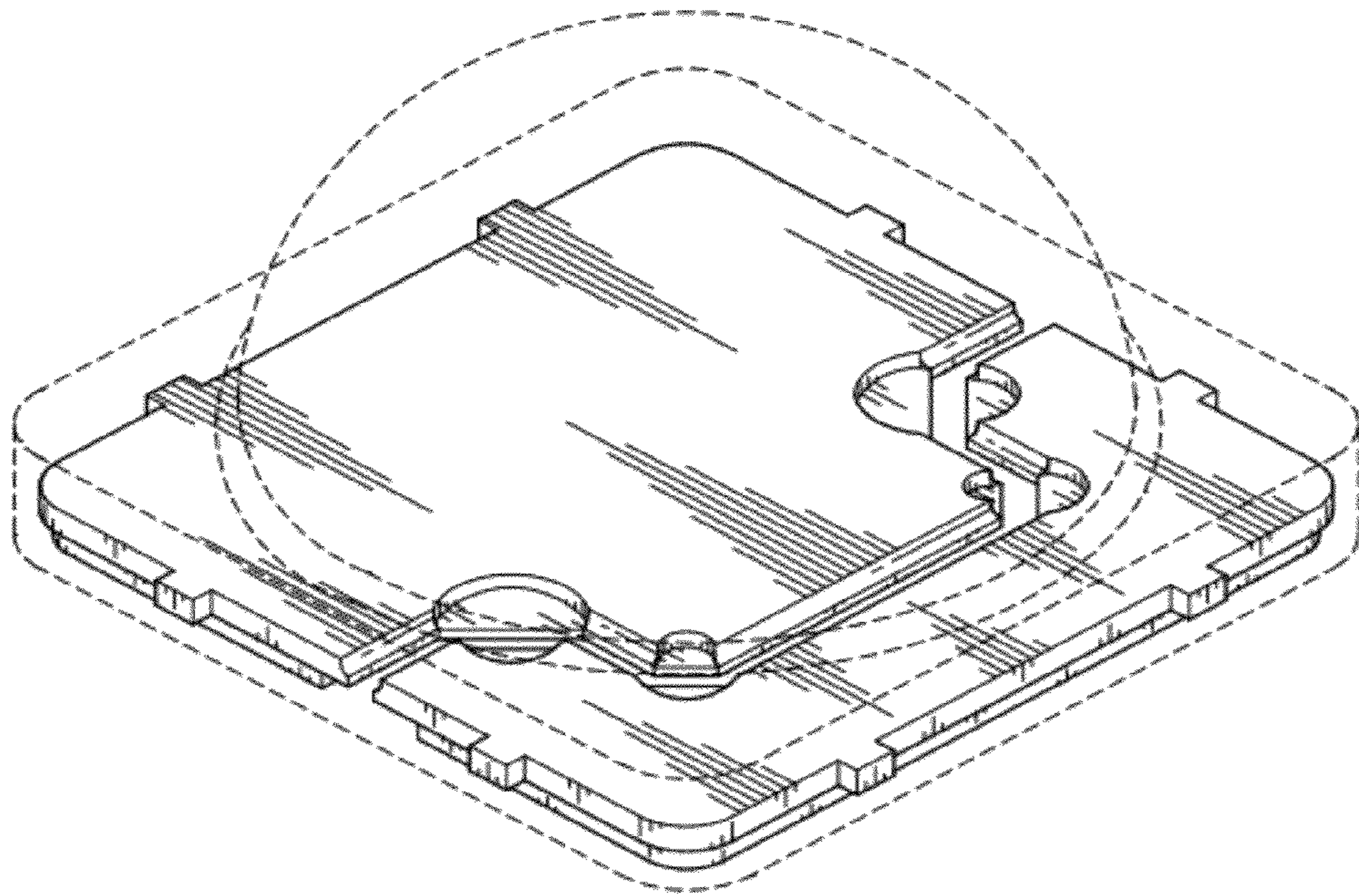


FIG. 1

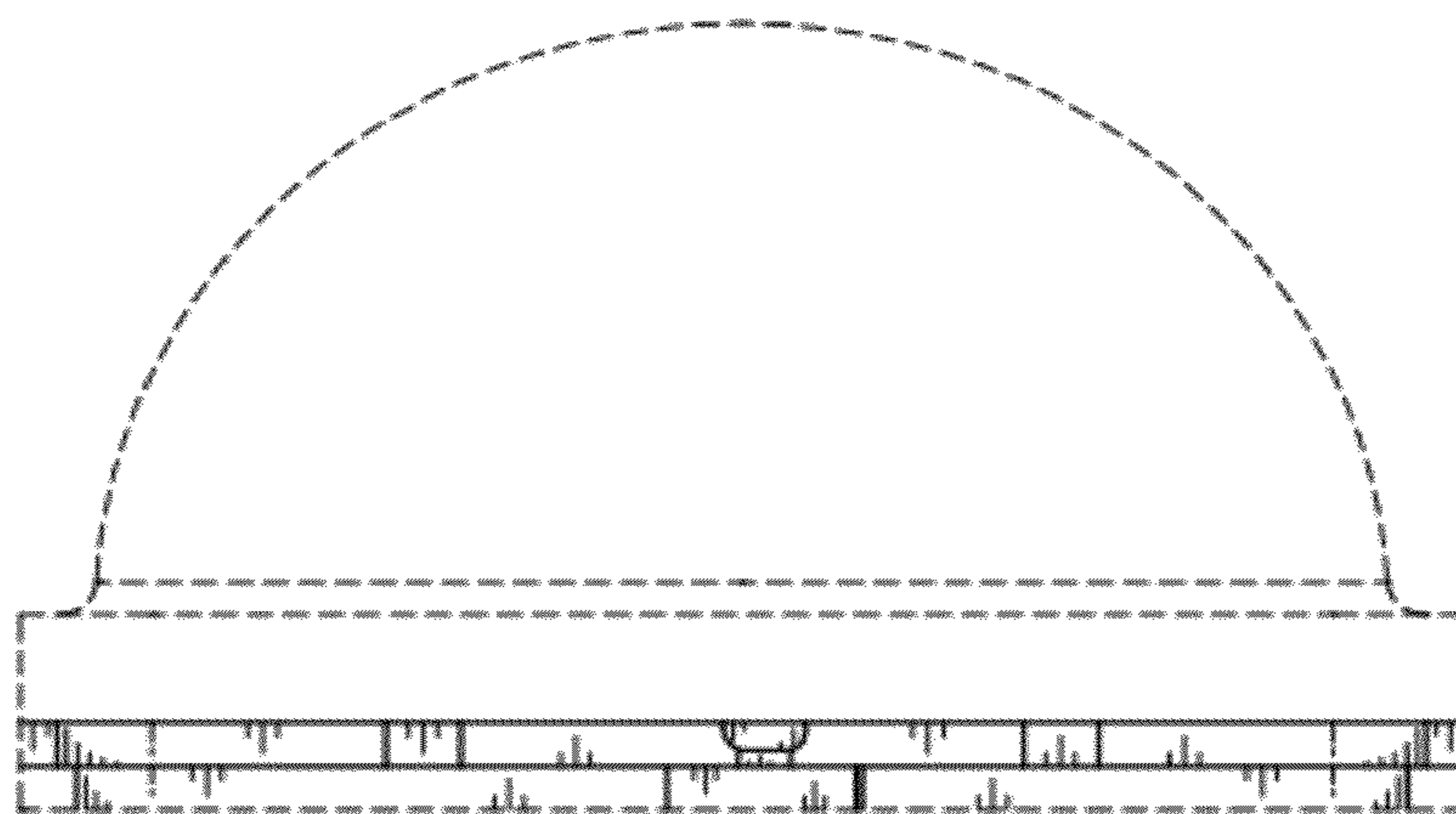


FIG. 2

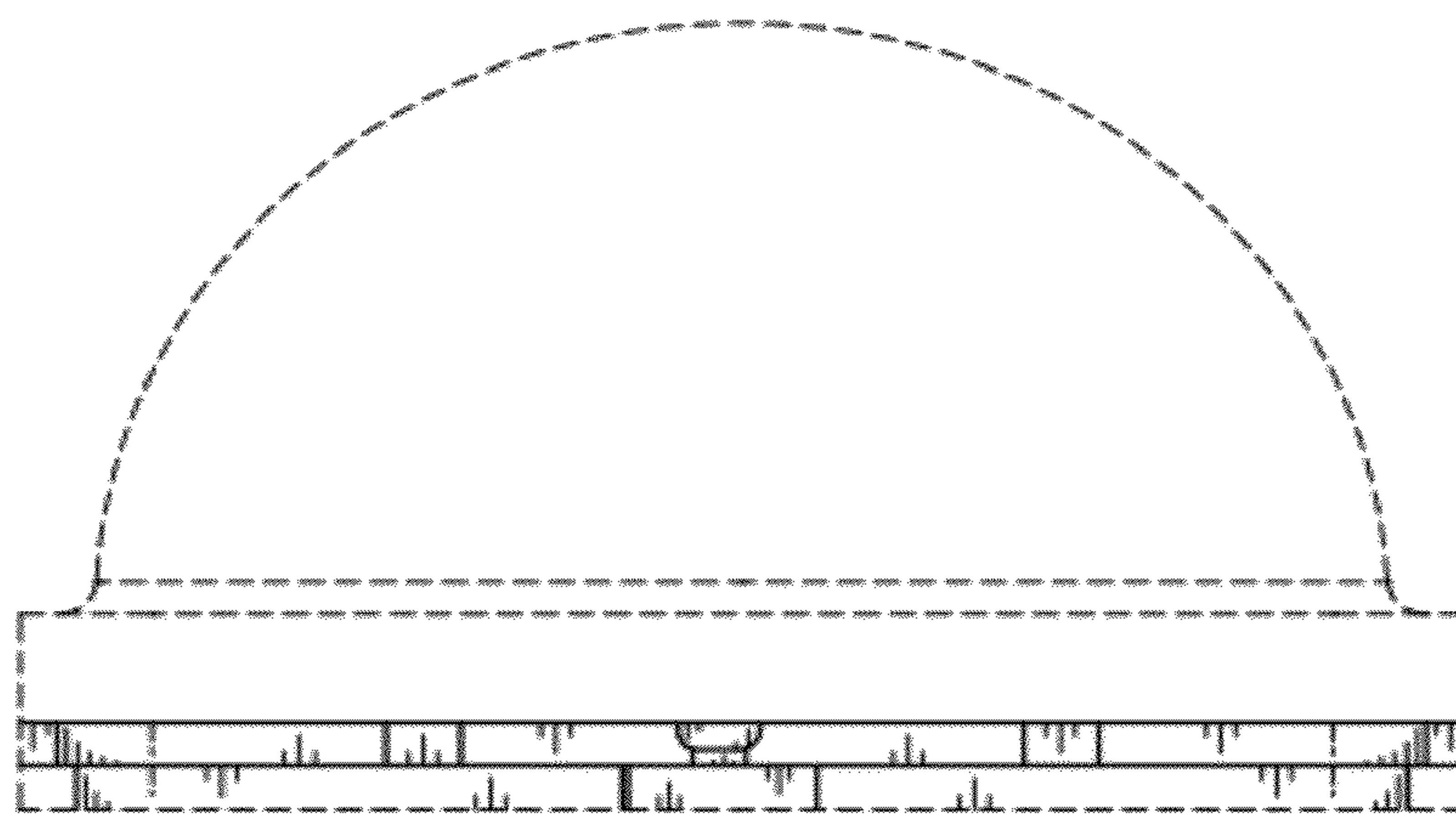


FIG. 3

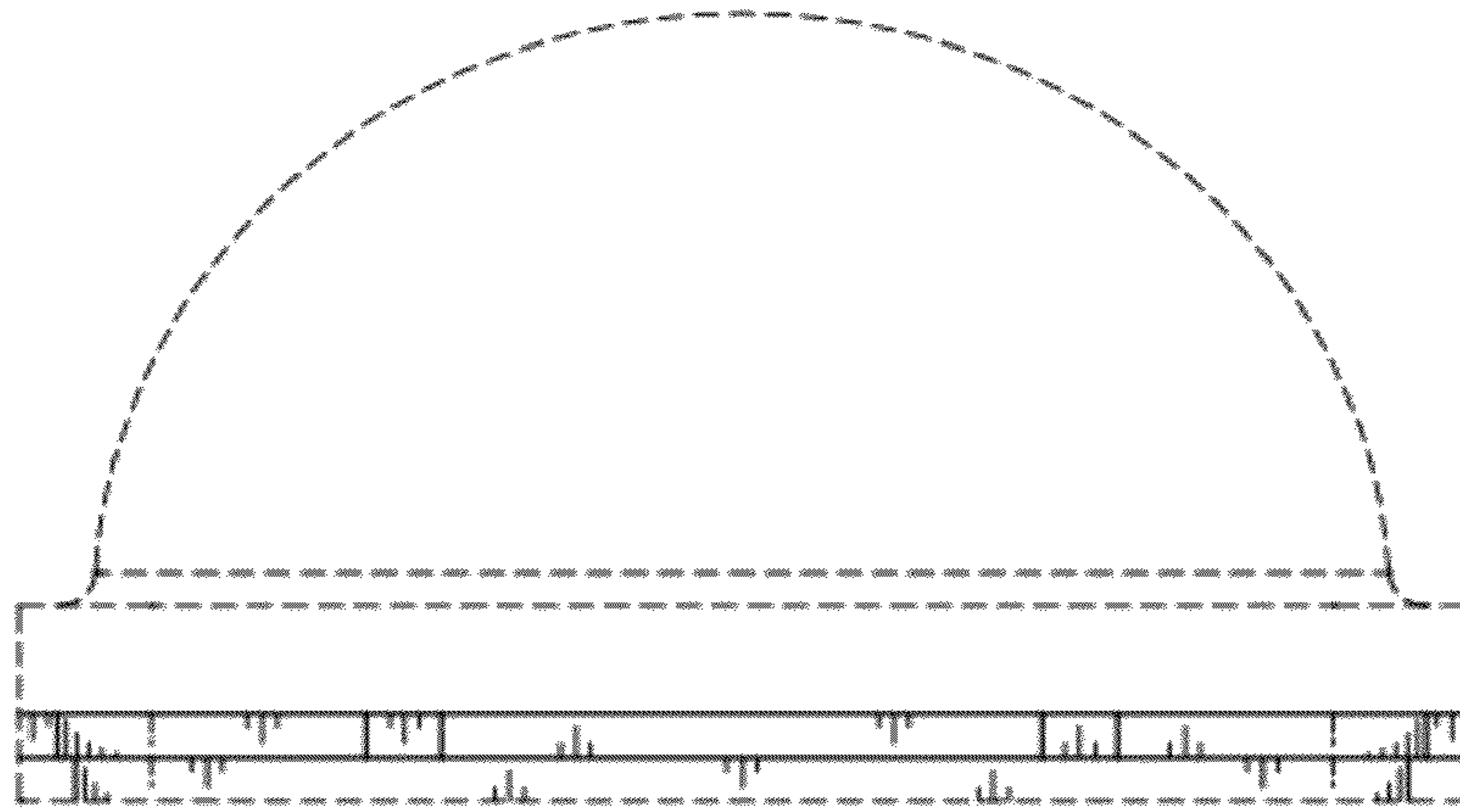


FIG. 4

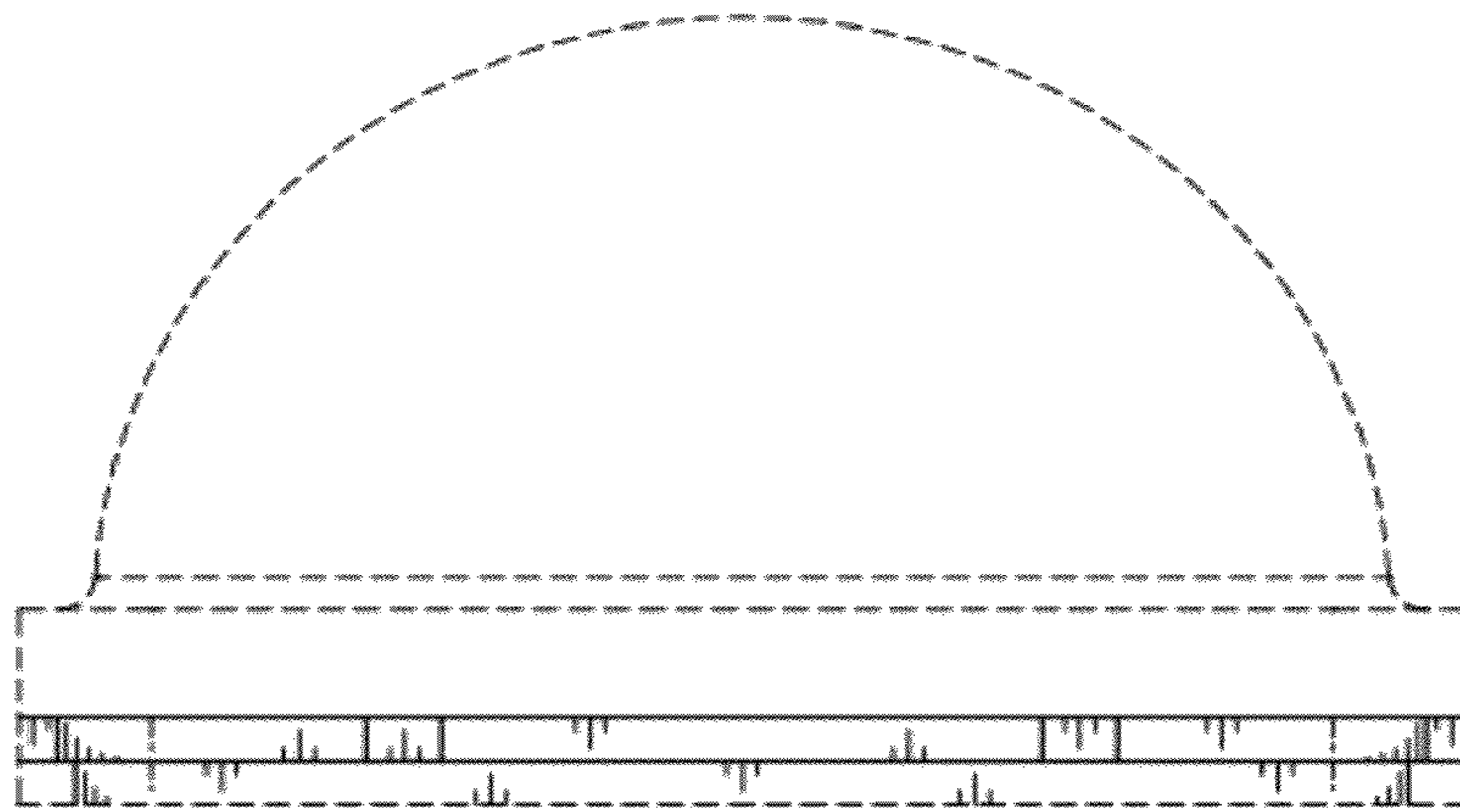


FIG. 5

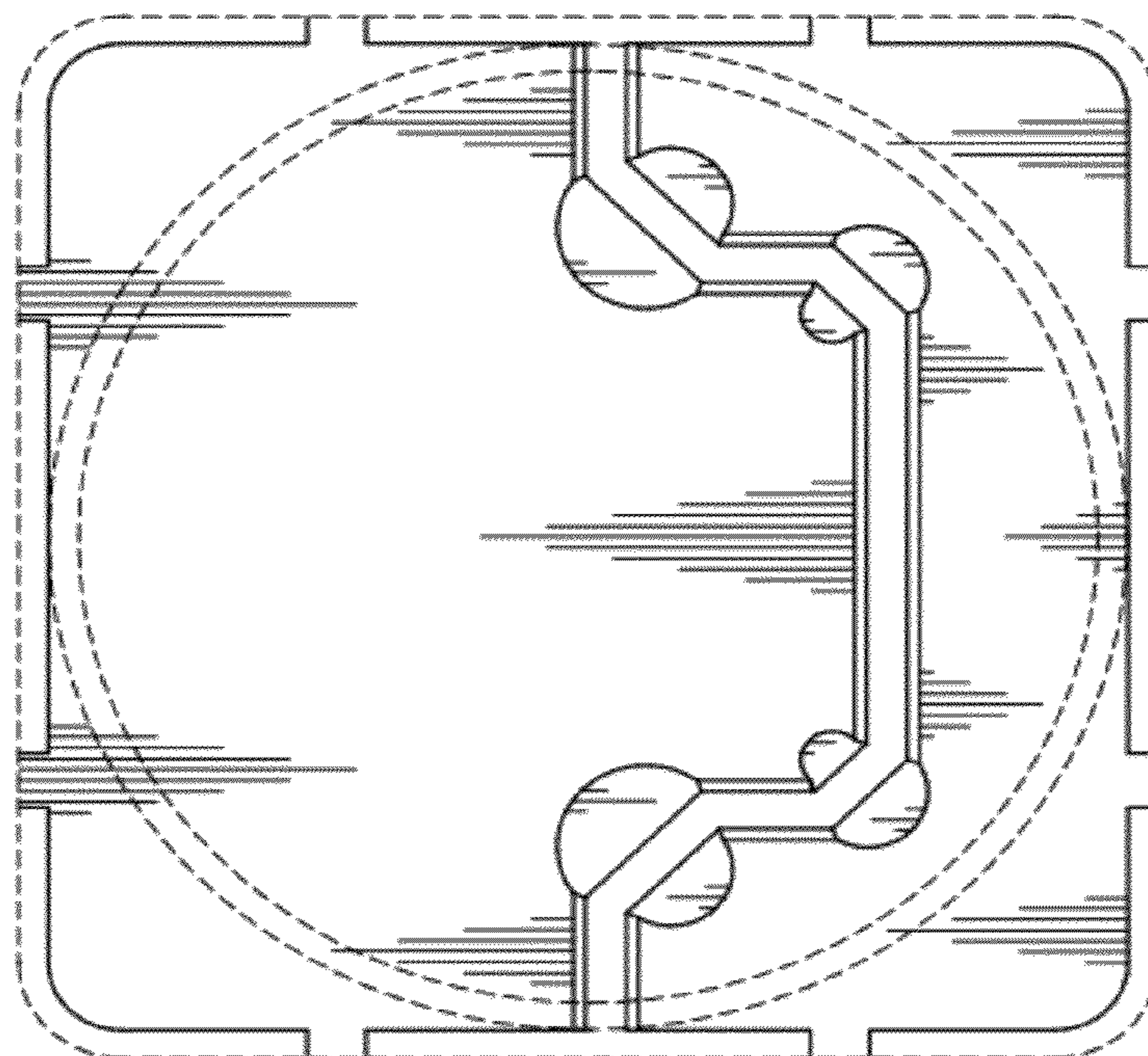


FIG. 6

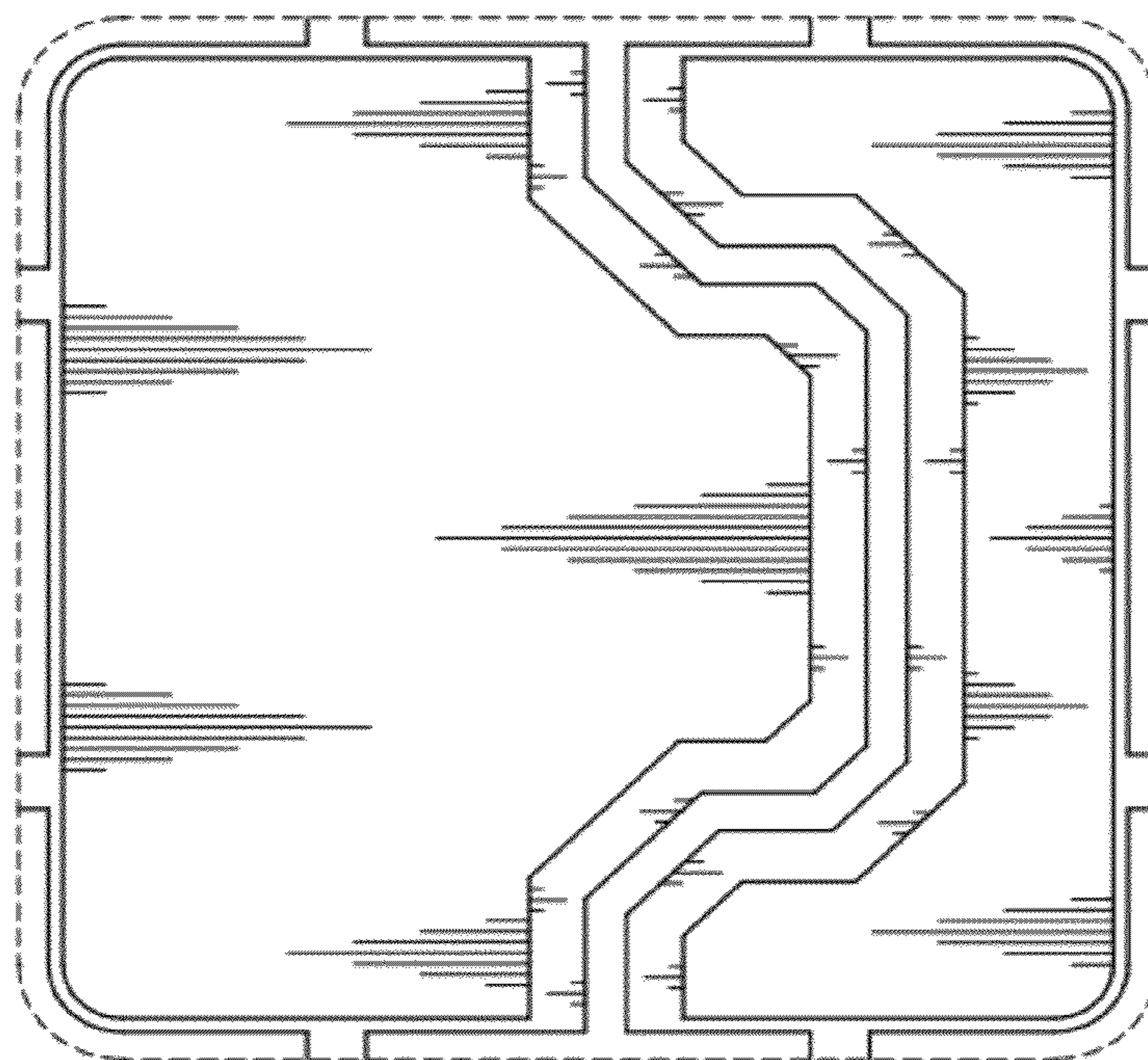


FIG. 7

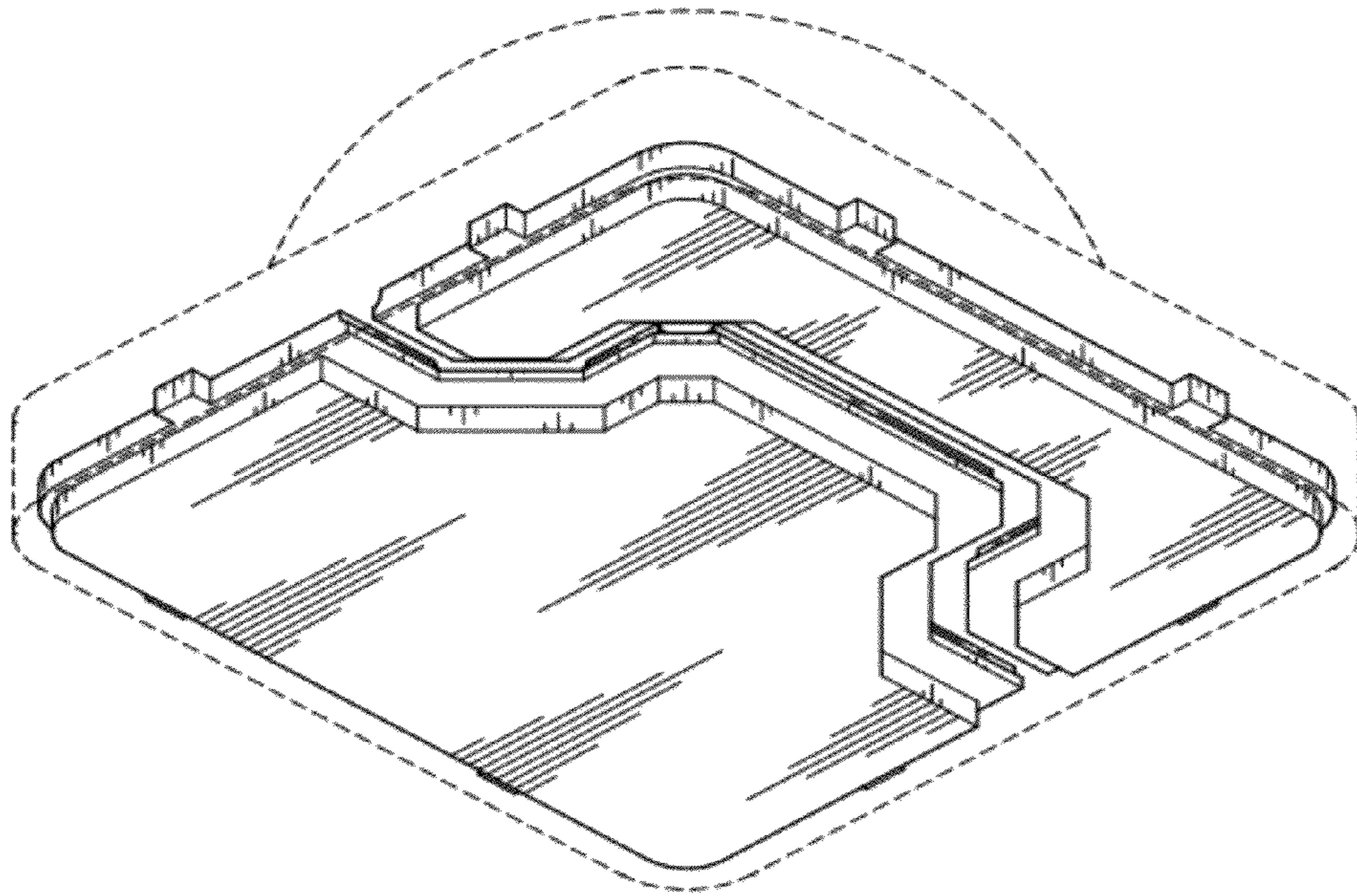


FIG. 8

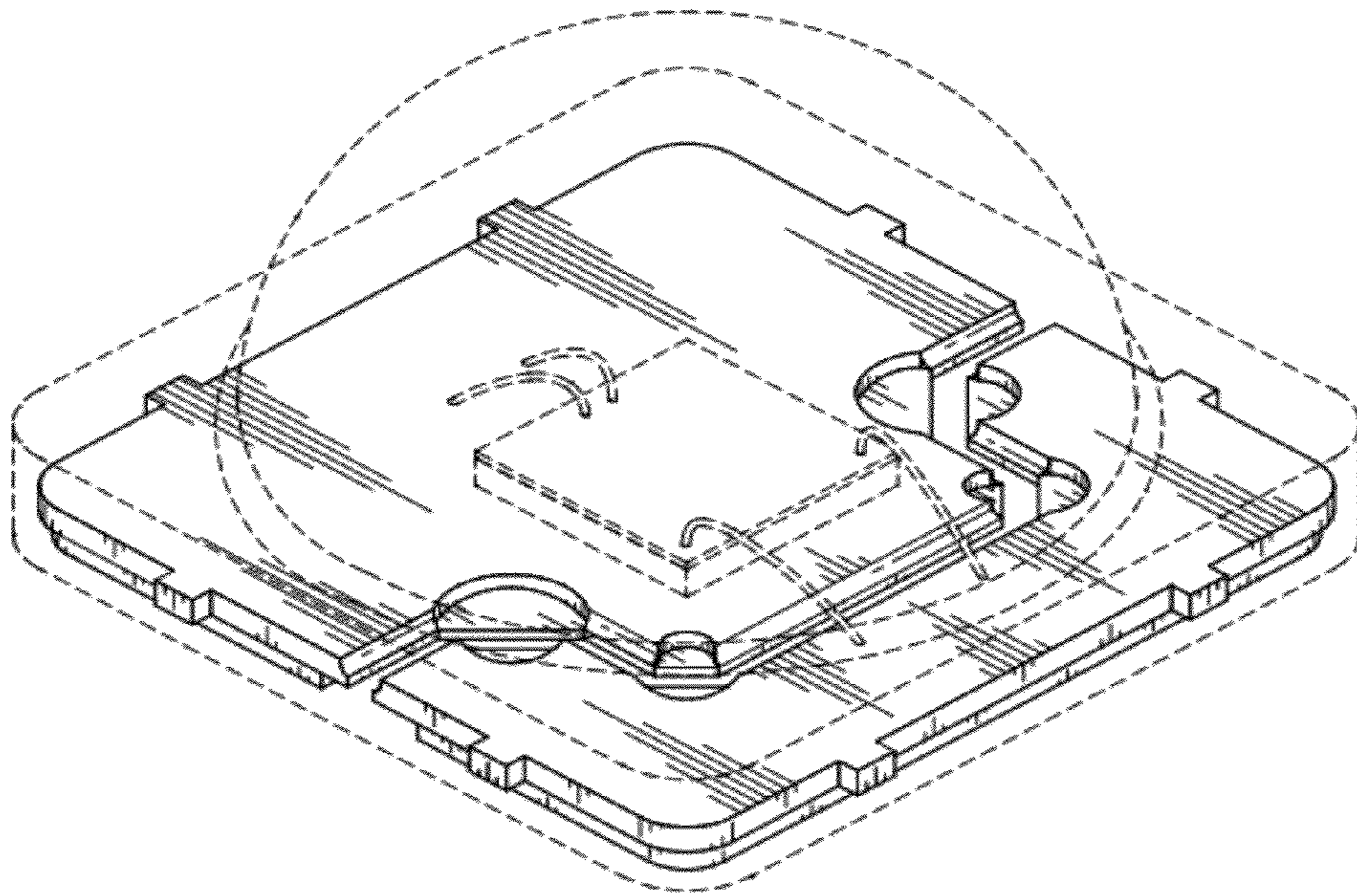


FIG. 9